

MSF16065G1

650V Silicon Carbide Diode

Features

- 650-Volt Schottky Rectifier
- Shorter recovery time
- High-speed switching possible
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on VF

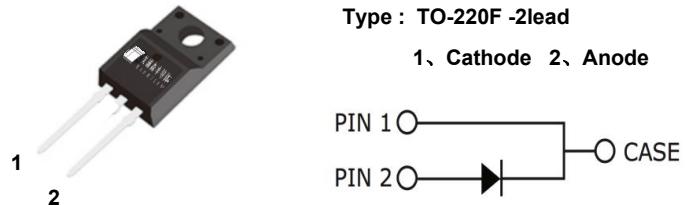
Benefits

- Higher safety margin against overvoltage
- Improved efficiency all load conditions
- Increased efficiency compared to Silicon Diode alternatives
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives
- HID Lighting

Package



Absolute Maximum Ratings

$T_C = 25^\circ C$ unless otherwise noted

| Symbol | Parameter | MSF16065G1 | Units |
|-----------|---|-------------|-------|
| VRRM | Repetitive Peak Reverse Voltage | 650 | V |
| VRSM | Surge Peak Reverse Voltage | 650 | V |
| VDC | DC Blocking Voltage | 650 | V |
| IF | Continuous Forward Current @ $T_C=150^\circ C$ | 16 | A |
| IFRM | Repetitive Peak Forward Surge Current @ $T_C=25^\circ C$ $t_p = 10$ ms, Half Sine Wave | 105 | A |
| IFSM | Non-Repetitive Peak Forward Surge Current @ $T_C=25^\circ C$ $t_p = 10$ ms, Half Sine Wave | 135 | A |
| IF,Max | Non-Repetitive Peak Forward Surge Current @ $T_C=25^\circ C$, $t_p = 10$ us | 1200 | A |
| Ptot | Power Dissipation @ $T_C=25^\circ C$ @ $T_C=110^\circ C$ | 205 89 | W |
| TJ , Tstg | Operating Junction and Storage Temperature | -55 to +175 | °C |

Electrical Characteristics

$T_C = 25^\circ C$ unless otherwise noted

| Symbol | Test Conditions | Test Conditions | Min | Typ | Max | Unit |
|--------|---------------------------|--|-----|-----------------|------------|---------|
| VF | Forward Voltage | IF=16A, $T_C=25^\circ C$ IF=16A, $T_C=175^\circ C$ | - | 1.45 1.75 | 1.8 3.0 | V |
| IR | Reverse Current | $VR=650V, T_C=25^\circ C$ $VR=650V, T_C=175^\circ C$ | - | 4 40 | 20 200 | μA |
| QC | Total Capacitive Charge | $VR = 400V, IF = 16A$ $T_J = 25^\circ C$ $Qc = \int_0^{V_r} C(V) dv$ | - | 41 | - | nC |
| C | Total Capacitance | $VR = 0V, TJ = 25^\circ C, f=1MHz$ $VR = 200V, TJ = 25^\circ C, f=1MHz$ $VR = 400V, TJ = 25^\circ C, f=1MHz$ | - | 860 85 60 | - | pF |
| EC | Capacitance Stored Energy | $VR=400V$ | - | 8.2 | - | μJ |

Thermal Characteristics

| Symbol | Parameter | Typ | Unit |
|------------------|--|------|------|
| R _{θJC} | Thermal Resistance from Junction to Case | 0.73 | °C/W |

Typical Characteristics

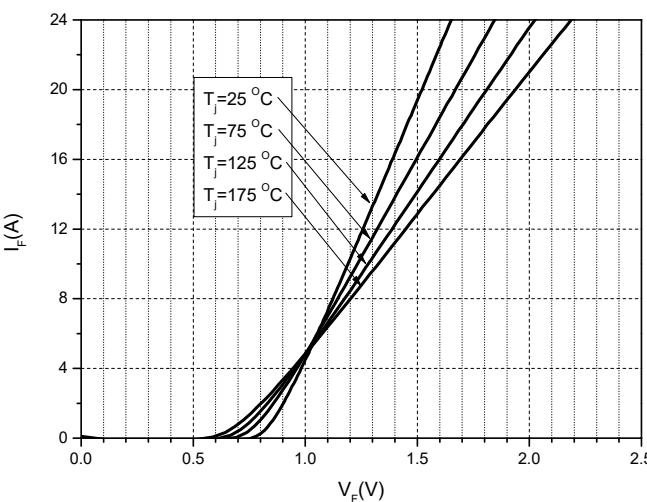


Figure 1. Forward Characteristics

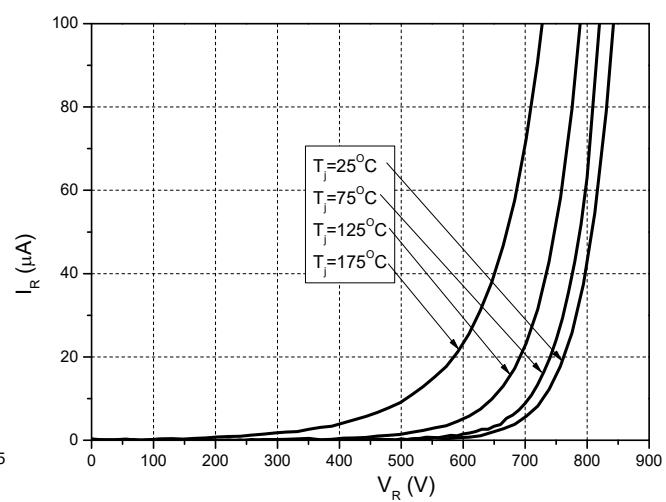


Figure 2. Reverse Characteristics

Typical Characteristics

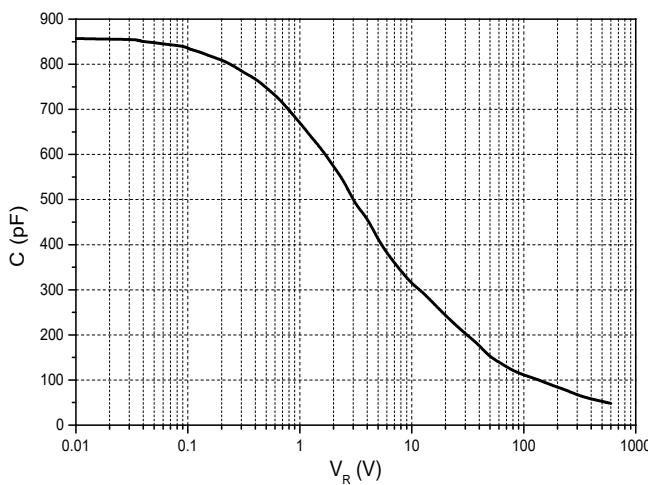


Figure 3. Capacitance vs. Reverse Voltage

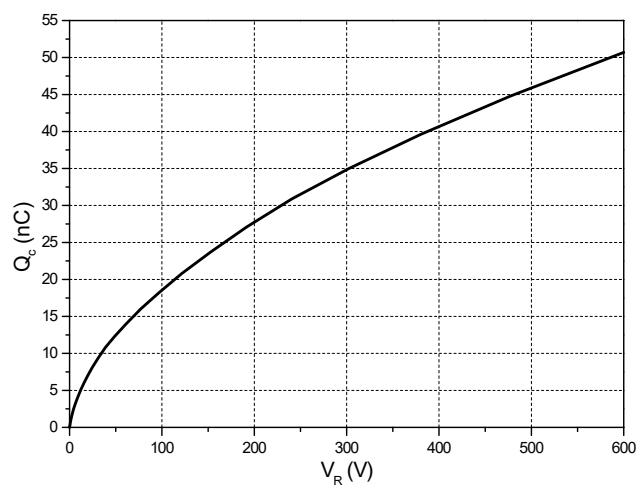


Figure 4. Total Capacitance Charge vs. Reverse Voltage

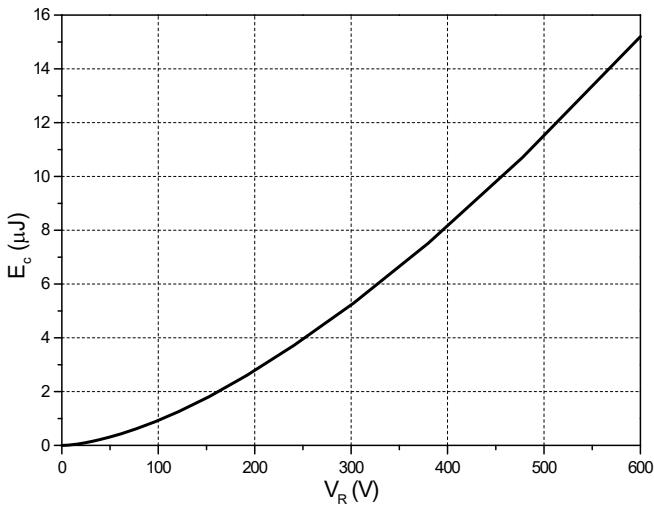


Figure 5. Capacitance Stored Energy

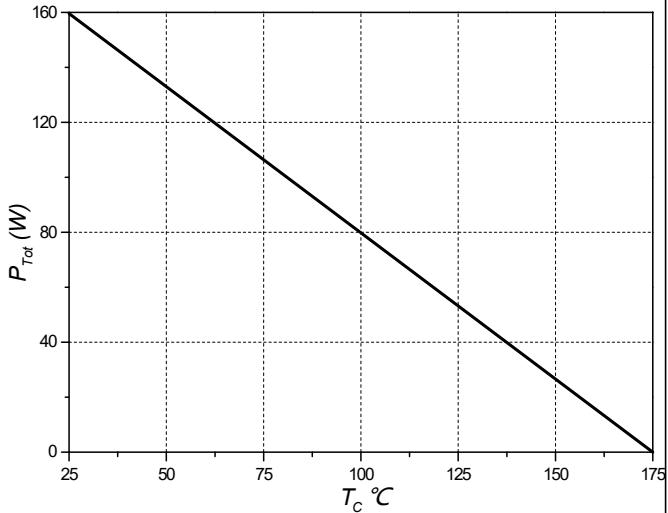


Figure 6. Power Derating

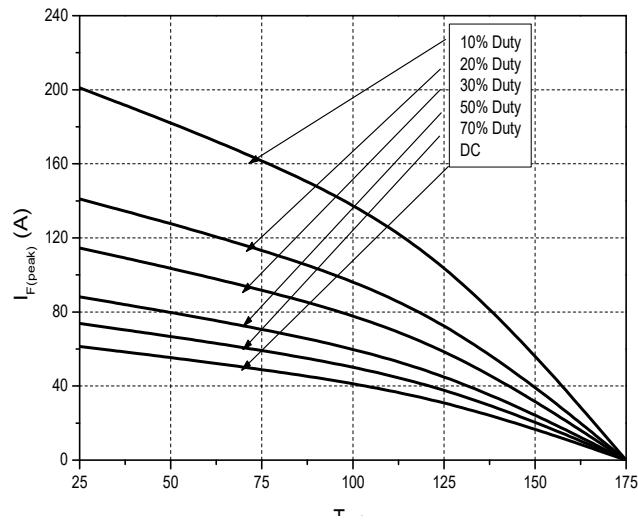


Figure 7. Current Derating

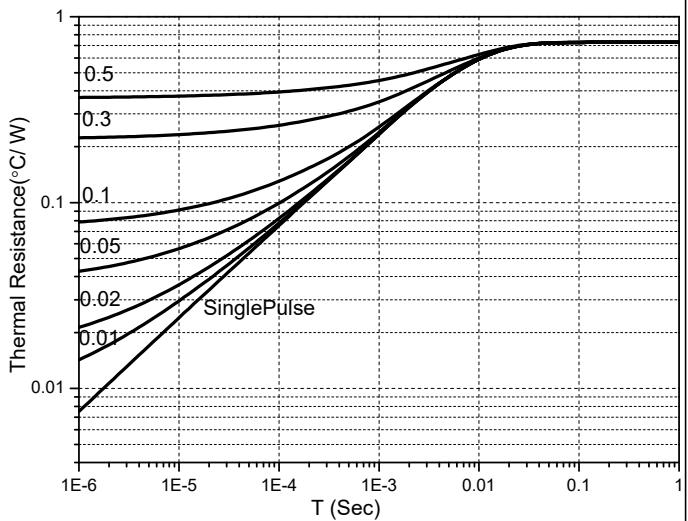
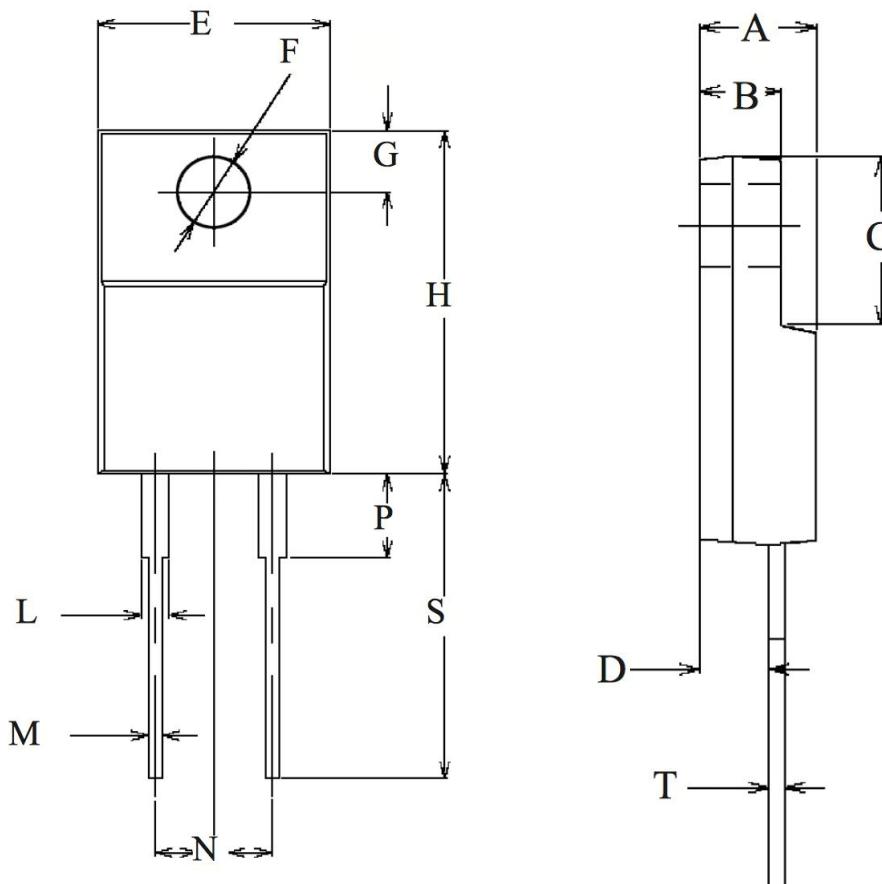


Figure 8. Transient Thermal Impedance

Package Dimensions TO-220F-2Lead



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max | | Min | Max | Min | Max |
| A | 4.5 | 4.93 | 0.177 | 0.194 | H | 15.67 | 16.07 | 0.617 | 0.633 |
| B | 2.34 | 2.74 | 0.092 | 0.108 | L | 1 | 1.4 | 0.039 | 0.055 |
| C | 6.5 | 6.9 | 0.256 | 0.272 | M | 0.4 | 0.91 | 0.016 | 0.036 |
| D | 2.5 | 2.96 | 0.098 | 0.117 | N | 5.08 TYP | | 0.200 TYP | |
| E | 9.9 | 10.36 | 0.39 | 0.408 | P | 1.9 | 3.9 | 0.114 | 0.154 |
| F | 2.98 | 3.4 | 0.117 | 0.134 | S | 12.1 | 13.18 | 0.476 | 0.519 |
| G | 3.1 | 3.5 | 0.122 | 0.138 | T | 0.4 | 0.8 | 0.016 | 0.031 |

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